

Quasi-Resonant Buck Controller for Precise Current Regulation and Wide Analog Dimming

NCL30076

The NCL30076 is a DC–DC buck controller for wide dimming range down to 1% by analog dimming control to relieve audible noise and flicker in PWM dimming. ON Semiconductor’s proprietary LED current calculation technique driven by zero input offset amplifiers performs precise constant current in the whole analog dimming range. Multi–mode operation provides high efficiency with minimized switching loss by QR at heavy load and deep analog dimming by DCM at light load.

PWM dimming control is also provided in case that constant LED color temperature is required. The NCL30076 has several protections such as LED short protection, over current protection, thermal shutdown and VDD over voltage protection for robust system reliability.

Features

- Wide Analog Dimming Range: 1~100%
- Low CC Tolerance: $\pm 2\%$ at 100% Load & $\pm 20\%$ at 1% Load
- Low System BOM
- LED Off Mode at Standby
- Low Standby Current
- PWM Dimming Available
- Gate Sourcing and Sinking Current of 0.5 A/0.8 A
- Robust Protection Features
 - ◆ LED Short Protection
 - ◆ Over Current Protection
 - ◆ Thermal Shutdown
 - ◆ V_{DD} Over Voltage Protection

Typical Applications

- LED Lighting System



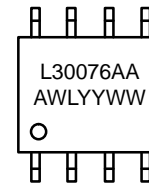
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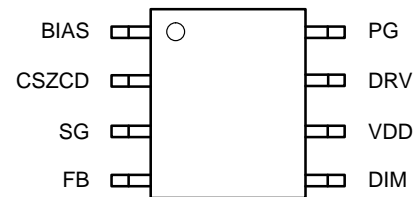
SOIC–8 NB
CASE 751

MARKING DIAGRAM



L30076 = Specific Device Code
 AA = Default Trimming Option
 A = Assembly Location
 WL = Wafer Lot Traceability Code
 YYWW = 4 Digit Data Code

PIN ASSIGNMENT



(Top View)

ORDERING INFORMATION

| Device | Package | Shipping |
|----------------|-----------|-----------------------|
| NCL30076AADR2G | SOIC–8 NB | 3000 / Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NCL30076

APPLICATION SCHEMATIC

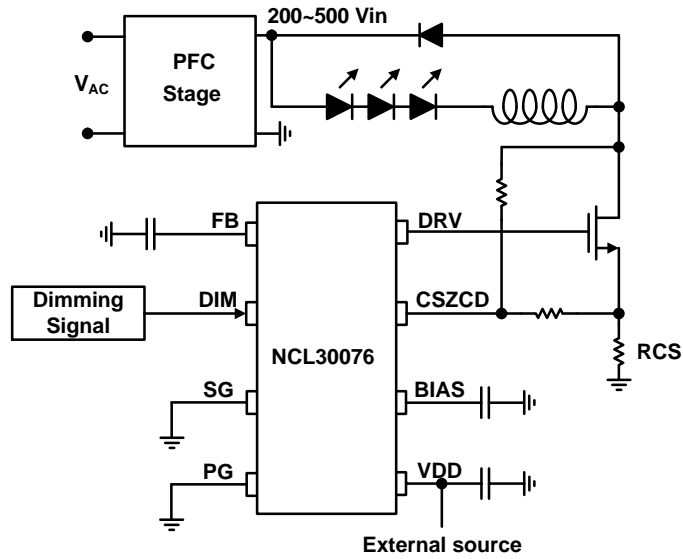


Figure 1. Application Schematic

BLOCK DIAGRAM

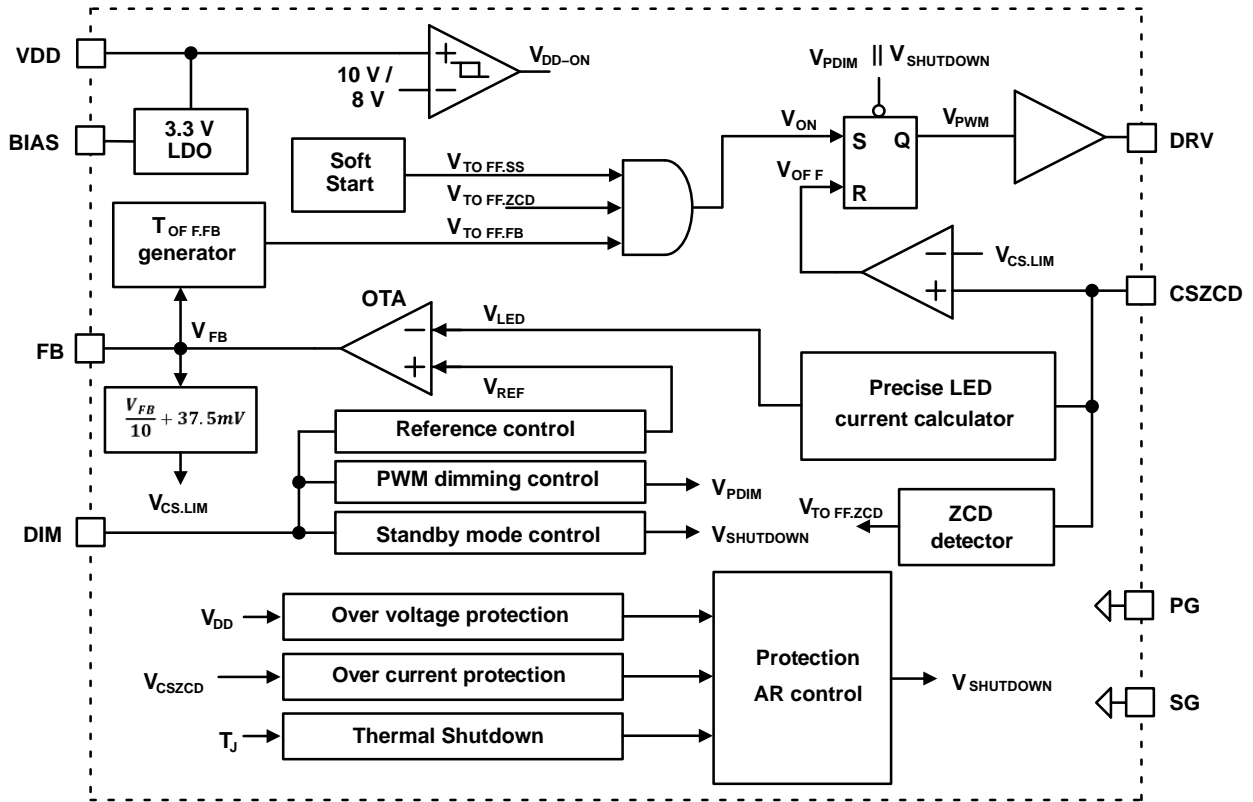


Figure 2. Simplified Block Diagram

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PIN CONFIGURATION

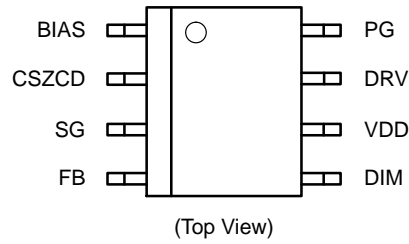


Figure 3. Pin Configuration

PIN FUNCTION DESCRIPTION

| Pin No. | Pin Name | Function | Description |
|---------|----------|--------------------|--|
| 1 | BIAS | 3.3 V BIAS | This pin is 3.3 V LDO output to bias the internal digital circuit |
| 2 | CSZCD | CS and ZCD Sensing | This pin detects the switch current and the inductor current zero cross time |
| 3 | SG | Signal Ground | Signal Ground is close to control pin circuit such as CSZCD, DIM and FB |
| 4 | FB | Feedback | Output of feedback OTA |
| 5 | DIM | Dimming Input | Dimming signal is provided to this pin |
| 6 | VDD | Power Supply | IC operating current is supplied to this pin |
| 7 | DRV | Output Drive | This pin is connected to drive external switch |
| 8 | PG | Power Ground | Power Ground is close to the capacitors at BIAS and VDD pin |

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SPECIFICATIONS

MAXIMUM RATINGS

| Parameter | Symbol | Value | Unit |
|--|-----------------|-------------|--------------------|
| VDD, DRV Pin Voltage Range | $V_{MV(MAX)}$ | -0.3 to 30 | V |
| DIM, FB, CSZCD, BIAS Pin Voltage Range | $V_{LV(MAX)}$ | -0.3 to 5.5 | V |
| Maximum Power Dissipation ($T_A < 50^\circ\text{C}$) | $P_{D(MAX)}$ | 550 | mW |
| Maximum Junction Temperature | $T_{J(max)}$ | 150 | $^\circ\text{C}$ |
| Storage Temperature Range | T_{STG} | -55 to 150 | $^\circ\text{C}$ |
| Junction-to-Ambient Thermal Impedance | $R_{\theta JA}$ | 145 | $^\circ\text{C/W}$ |
| ESD Capability, Human Body Model (Note 2) | ESD_{HBM} | 2 | kV |
| ESD Capability, Charged Device Model (Note 2) | ESD_{CDM} | 1 | kV |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Refer to ELECTRICAL CHARACTERISTICS, RECOMMENDED OPERATING RANGES and/or APPLICATION INFORMATION for Safe Operating parameters.
- This device series incorporates ESD protection and is tested by the following methods:
 - ESD Human Body Model per JEDEC Standard JESD22-A114
 - ESD Charged Device Model per JEDEC Standard JESD22-C101
 - Latch-up Current Maximum Rating ± 100 mA per JEDEC Standard JESD78

RECOMMENDED OPERATING RANGES

| Parameter | Symbol | Min | Max | Unit |
|----------------------|--------|-----|-----|------------------|
| Junction Temperature | T_J | -40 | 125 | $^\circ\text{C}$ |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

ELECTRICAL CHARACTERISTICS ($V_{DD} = 15$ V and $T_J = -40$ ~ 125°C unless otherwise specified)

| Parameter | Test Conditions | Symbol | Min | Typ | Max | Unit |
|-----------|-----------------|--------|-----|-----|-----|------|
|-----------|-----------------|--------|-----|-----|-----|------|

VDD SECTION

| | | | | | | |
|-------------------------------|-------------------------------|---------------|-----|------|------|---------------|
| IC Turn-On Threshold Voltage | | $V_{DD(ON)}$ | 9.3 | 10.0 | 10.7 | V |
| IC Turn-Off Threshold Voltage | | $V_{DD(OFF)}$ | 7.4 | 8.0 | 8.6 | V |
| Startup Current | $V_{DD} = V_{DD(ON)} - 1.6$ V | $I_{DD(ST)}$ | - | 250 | 400 | μA |
| Operating Current | | $I_{DD(OP)}$ | - | 6.5 | 8.0 | mA |
| Standby Current | | $I_{DD(SB)}$ | - | 200 | 300 | μA |

BIAS SECTION

| | | | | | | |
|--------------|---|------------|------|------|------|---|
| BIAS Voltage | | V_{BIAS} | 3.23 | 3.30 | 3.37 | V |
| | $T_J = 25$ ~ 100°C (Note 4) | | 3.25 | 3.30 | 3.35 | |

DIM SECTION

| | | | | | | |
|--------------------------------|-------------------|--------------------|-------|------|-------|----|
| DIM Voltage for 100% V_{REF} | $V_{DIM} = 1.9$ V | $V_{DIM(REF-MAX)}$ | 1.755 | 1.80 | 1.845 | V |
| DIM Voltage for 99% V_{REF} | | $V_{DIM(MAX-EFF)}$ | 1.730 | 1.78 | 1.827 | V |
| Standby Enabling DIM Voltage | | $V_{DIM(SB-ENA)}$ | 50 | 75 | 100 | mV |
| Standby Disabling DIM Voltage | | $V_{DIM(SB-DIS)}$ | 60 | 100 | 140 | mV |
| Standby Delay Time | | $t_{SB(DELAY)}$ | 9 | 10 | 11 | ms |

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ELECTRICAL CHARACTERISTICS ($V_{DD} = 15\text{ V}$ and $T_J = -40\text{--}125^\circ\text{C}$ unless otherwise specified) (continued)

| Parameter | Test Conditions | Symbol | Min | Typ | Max | Unit |
|-----------|-----------------|--------|-----|-----|-----|------|
|-----------|-----------------|--------|-----|-----|-----|------|

FB SECTION

| | | | | | | |
|-----------------------------|---|------------------|-------|-------|------|-----------------|
| FB OTA Source Current | $I_{FB} = (V_{LED} - V_{REF}) \times g_{M(FB)} \times 10$ $V_{REF} = 150\text{ mV}, V_{LED} = 100\text{ mV}$ | $I_{FB(SOURCE)}$ | -14.0 | -11.5 | -9.0 | μA |
| FB OTA Sink Current | $I_{FB} = (V_{LED} - V_{REF}) \times g_{M(FB)} \times 10$ $V_{REF} = 50\text{ mV}, V_{LED} = 100\text{ mV}$ | $I_{FB(SINK)}$ | 9.0 | 11.5 | 14.0 | μA |
| FB OTA Transconductance | $g_{M(FB)} = I_{FB} / \{(V_{REF} - V_{LED}) \times 10\}$ | $g_{M(FB)}$ | 18 | 23 | 28 | μmho |
| FB OTA High Voltage | $V_{REF} = 150\text{ mV}, V_{LED} = 100\text{ mV}$ | $V_{FB(HIGH)}$ | 4.7 | - | - | V |
| FB Minimum Clamping Voltage | $V_{REF} = 0\text{ mV}, V_{LED} = 100\text{ mV}$ | $V_{FB(CLP)}$ | 0.4 | 0.5 | 0.6 | V |

CS SECTION

| | | | | | | |
|--------------------------|--|-------------------|-----|-----|-----|----|
| CS Regulation | | $V_{CS(REG-MAX)}$ | 155 | 160 | 165 | mV |
| CS Current Limit Maximum | | $V_{CS(LIM-MAX)}$ | 390 | 410 | 430 | mV |
| CS Current Limit Minimum | | $V_{CS(LIM-MIN)}$ | 145 | 155 | 165 | mV |

DUTY SECTION

| | | | | | | |
|---------------------------------------|-------------------------|--------------------|------|------|------|---------------|
| Leading Edge Blanking Time at Turn-on | | $t_{LEB(TON)}$ | 360 | 400 | 440 | ns |
| Maximum Ton Time | | $t_{ON(MAX)}$ | 45 | 50 | 55 | μs |
| Minimum Toff Time | $V_{FB} = 3.8\text{ V}$ | $t_{OFF(MIN)}$ | 900 | 1250 | 1500 | ns |
| Maximum Toff Time | $V_{FB} = 0.5\text{ V}$ | $t_{OFF(MAX)}$ | 1.17 | 1.30 | 1.43 | ms |
| Maximum FB Voltage for Min. Toff | | $V_{FB(MAX-TOFF)}$ | 3.30 | 3.43 | 3.55 | V |
| Minimum FB Voltage for Max. Toff | | $V_{FB(MIN-TOFF)}$ | 0.9 | 1.1 | 1.3 | V |
| Quasi-Resonant Delay Time | | t_{QR} | 0.45 | 0.50 | 0.55 | μs |

DRV SECTION

| | | | | | | |
|------------------|---------------------------|-----------------|----|-----|-----|----|
| DRV Low Voltage | | $V_{DRV(LOW)}$ | - | - | 0.2 | V |
| DRV High Voltage | $V_{DD} = 15\text{ V}$ | $V_{DRV(HIGH)}$ | 11 | 12 | 13 | V |
| DRV Rising Time | $C_{DRV} = 3.3\text{ nF}$ | $t_{DRV(R)}$ | 60 | 100 | 145 | ns |
| DRV Falling Time | $C_{DRV} = 3.3\text{ nF}$ | $t_{DRV(F)}$ | 25 | 55 | 105 | ns |

AUTO RESTART SECTION

| | | | | | | |
|---------------------------------|--|----------------|-----|-----|-----|---|
| Auto Restart Time at Protection | | $t_{AR(PROT)}$ | 0.9 | 1.0 | 1.1 | s |
|---------------------------------|--|----------------|-----|-----|-----|---|

VDD OVER VOLTAGE PROTECTION SECTION

| | | | | | | |
|------------------------------------|--|---------------|----|----|----|---|
| VDD Over Voltage Threshold Voltage | | $V_{DD(OVP)}$ | 22 | 23 | 24 | V |
|------------------------------------|--|---------------|----|----|----|---|

OVER CURRENT PROTECTION SECTION

| | | | | | | |
|--------------------------------------|--|---------------|-----|-----|-----|---|
| CS Over Current Protection Threshold | | $V_{CS(OCP)}$ | 0.9 | 1.0 | 1.1 | V |
|--------------------------------------|--|---------------|-----|-----|-----|---|

THERMAL SHUTDOWN SECTION

| | | | | | | |
|--|--|---------------|-----|-----|-----|------------------|
| Thermal Shut Down Temperature (Note 3) | | T_{SD} | 130 | 150 | 170 | $^\circ\text{C}$ |
| Thermal Shut Down Hysteresis (Note 3) | | $T_{SD(HYS)}$ | 25 | 30 | 35 | $^\circ\text{C}$ |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Guaranteed by design.

4. Guaranteed by characterization.

TYPICAL CHARACTERISTICS

(These characteristic graphs are normalized at $T_A = 25^\circ\text{C}$)

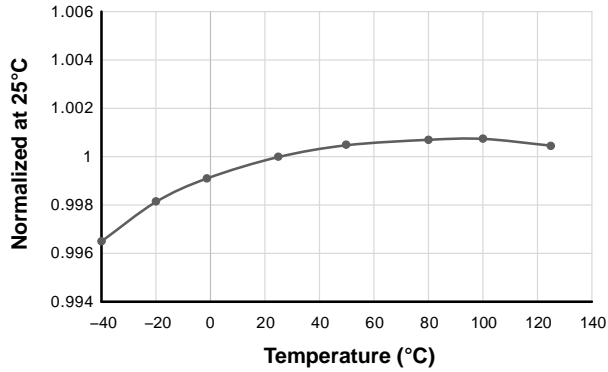


Figure 4. V_{BIAS} vs. Temperature

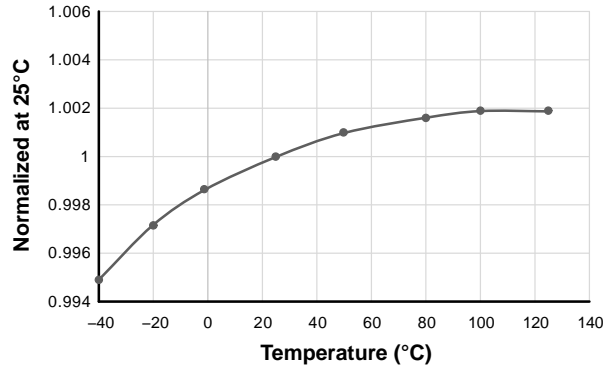


Figure 5. $V_{DIM(MAX)}$ vs. Temperature

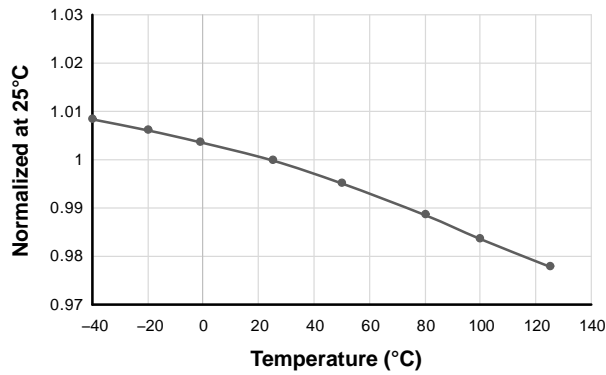


Figure 6. $g_{M(FB)}$ vs. Temperature

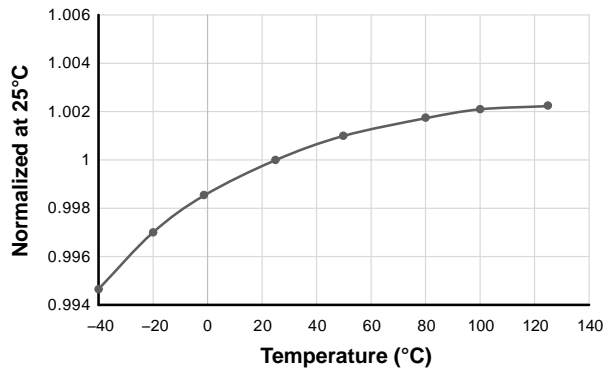


Figure 7. $V_{CS(REG-MAX)}$ vs. Temperature

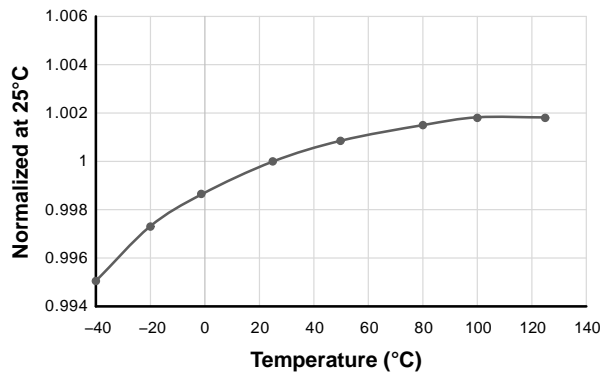


Figure 8. $V_{CS(LIM-MIN)}$ vs. Temperature

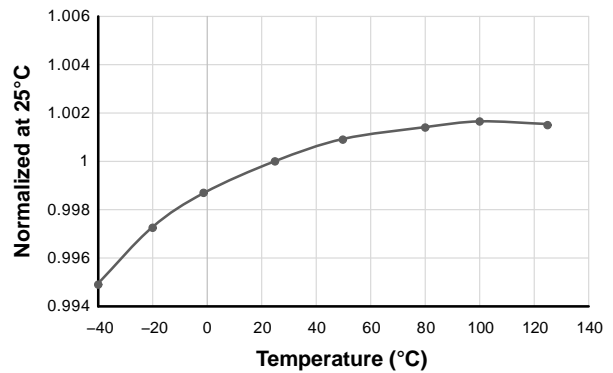


Figure 9. $V_{DD(OVP)}$ vs. Temperature

APPLICATION INFORMATION

General

NCL30076 provides wide analog dimming down to 1% with accurate CC regulation. According to buck inductor, input voltage and output voltage, deep dimming down to 0.1~0.2% load can be achieved. Thanks to ON Semiconductor's proprietary LED current calculation technique, NCL30076 is able to sense the current of LED load connected at input voltage node with no upper limit of the input voltage with high design flexibility and system reliability. LED current sensed by internal zero input offset amplifiers performs accurate CC regulation in the whole analog dimming range. Therefore, CC tolerance is tightly controlled within $\pm 2\%$ at 100% load and $\pm 20\%$ at 1% load.

Wide Analog Dimming

Wide analog dimming range is obtained by transitioning multi-mode operation between QR and DCM according to the dimming condition. At full load condition, QR with valley switching minimizes switching loss for high system efficiency and DCM is activated at light load condition to perform deep analog dimming. Internal LED current calculator and a digital compensator provide dimming linearity over the entire dimming range.

PWM Dimming

Analog dimming has benefits for less audible noise and flicker compared to PWM dimming. However, PWM dimming method is generally required to keep the constant LED color temperature in specific applications. NCL30076 supports PWM dimming by simply providing PWM dimming signal to DIM pin.

Precise CC Regulation

CC regulation is very important especially in programmable LED driver system to keep constant LED current under system variation of LED load, inductor, temperature, etc. NCL30076 applies zero input offset amplifiers at LED current calculator and OTA. Those blocks can implement precise LED current sensing and FB voltage generation.

Therefore, NCL30076 supports low CC tolerance less than $\pm 2\%$ at full load and $\pm 20\%$ at 1% load in the system variation.

Soft start

At startup, an internal soft start block gradually reduces T_{OFF} time from maximum T_{OFF} limit so that LED current is settled smoothly without overshoot current and unexpected flash.

Standby Mode

When V_{DIM} is lower than a standby threshold voltage for 10 ms, standby mode is triggered with LED turn-off and IC current consumption is minimized.

Auto Restart (AR) at Protection

Once protection is triggered, IC operation stops for 1 second and begins soft start operation after the auto restart time delay.

VDD Over Voltage Protection (OVP)

When VDD is higher than $V_{DD(OVP)}$ threshold, over voltage protection is triggered.

Short LED Protection (SLP)

When LED is short circuited, the buck stage operates at minimum switching frequency, so the maximum turn-off time control protects the freewheeling diode from thermal stress.

Over Current Protection (OCP)

When CSZCD voltage exceeds the over current threshold voltage, switching is immediately shut down after leading edge blanking time in the short circuit condition of the inductor or the freewheeling diode.

Thermal Shot Down (TSD)

When IC junction temperature is higher than 150°C , TSD is triggered and released when the temperature is lower than 120°C .

BASIC OPERATION

NCL30076 is the current mode buck controller in which DRV is off when V_{CSZCD} reaches to $V_{CS.LIM}$ and DRV is on by inductor current zero cross signal ($V_{TOFF.ZCD}$) in QR and $T_{OFF.FB}$ generator output ($V_{TOFF.FB}$) in DCM as shown in Figure 10. V_{LED} is calculated based on V_{CSZCD} in precise LED current calculator block composed of zero input offset amplifiers and V_{REF} is controlled by DIM signal by below equation.

$$V_{REF} [V] = \frac{V_{DIM} - 0.2 V}{10} \quad (eq. 1)$$

V_{LED} is compared with V_{REF} by OTA to generate V_{FB} . V_{FB} sets $V_{CS.LIM}$ as below equation.

$$V_{CS.LIM} [V] = \frac{V_{FB}}{10} + 37.5 mV \quad (eq. 2)$$

V_{FB} also controls $V_{TOFF.FB}$ signal by $T_{OFF.FB}$ generator in which $V_{TOFF.FB}$ is triggered at $T_{OFF.FB}$ after DRV is turned off.

$$T_{OFF.FB} [\mu s] = \frac{2.7}{V_{FB} - 1.1} + 0.1 \quad (eq. 3)$$

When V_{CSZCD} drops after the inductor current zero cross, IC counts t_{QR} (0.5 μs) and trigger $V_{TOFF.ZCD}$. In QR mode, $V_{TOFF.ZCD}$ signal is generated later than $V_{TOFF.FB}$ signal and DRV on is determined by $V_{TOFF.ZCD}$ for valley switching. In DCM mode, DRV on is set by $V_{TOFF.FB}$ as $T_{OFF.FB}$ is longer than $V_{TOFF.ZCD}$ triggering time.

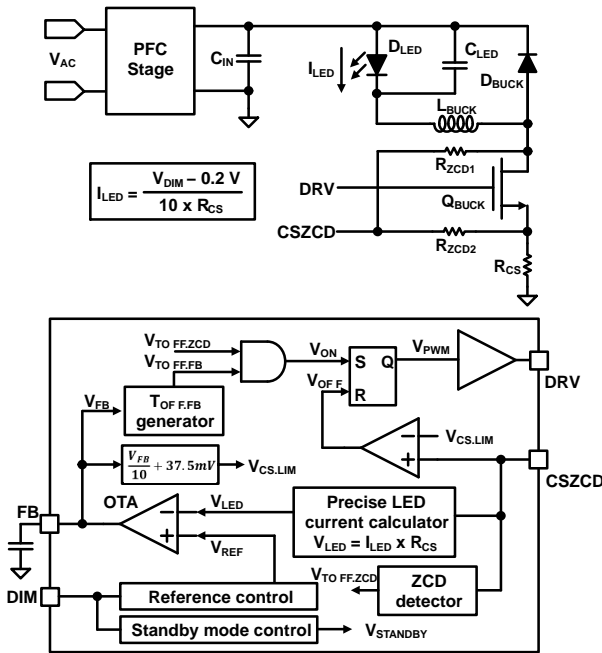


Figure 10. NCL30076 Block Diagram

Wide Analog Dimming

NCL30076 operates in QR at full load and in DCM at light load for a wide dimming range. Figure 11 shows how NCL30076 operates with V_{DIM} .

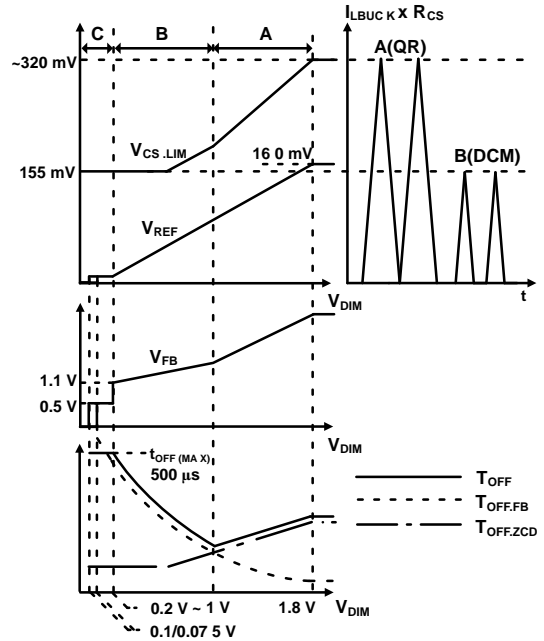


Figure 11. Operation Mode vs. V_{DIM}

- **A:** V_{FB} controls $V_{CS.LIM}$ and T_{OFF} is determined by $T_{OFF.ZCD}$ with QR switching as $T_{OFF.ZCD}$ is longer than $T_{OFF.FB}$.
- **B:** Operating mode is transitioned from QR to DCM at the boundary between A and B region which is approximately half load. T_{OFF} is determined by $T_{OFF.FB}$ as $T_{OFF.FB}$ is longer than $T_{OFF.ZCD}$. When V_{DIM} is further reduced, $V_{CS.LIM}$ is no longer controlled by V_{FB} and clamped to minimum $V_{CS.LIM}$ (155 mV).
- **C:** When V_{DIM} is lower than 0.2 V, V_{REF} is set to 0 V and V_{FB} is pulled down to 0.5 V clamping voltage with min. LED current under open loop control. When V_{DIM} is lower than 0.075/0.1 V, standby mode is triggered with LED turn-off.

Precise CC Regulation

Current sensing amplifier and OTA applies zero input offset compensation technique for precise CC regulation and dimming curve linearity in multi-mode operation

Table 1 shows CC tolerance measured by changing inductor ($\pm 15\%$), temperature ($-10, 25, 90^\circ C$), output voltage (100, 200, 300 V) and controller 150 pcs (3 lot variation) in 400 V input 100 W driver. As a result, CC tolerance with system variables at 1% deep dimming condition is less than $\pm 26\%$ and less than $\pm 3.0\%$ at full load condition.

Table 1. CC TOLERANCE (150 pcs)

| Inductor : ±15% Temp. : -10 / 25 / 90 °C | 100% Load | 50% Load | 10% Load | 5% Load | 2% Load | 1% Load |
|---|-----------|----------|----------|---------|---------|---------|
| V _{OUT} : 100 V | 1.99 | 3.77 | 4.41 | 5.32 | 9.22 | 16.23 |
| V _{OUT} : 200 V | 1.83 | 3.70 | 4.76 | 5.23 | 8.64 | 14.44 |
| V _{OUT} : 300 V | 1.86 | 3.06 | 4.33 | 5.80 | 10.57 | 20.54* |
| V _{OUT} : 100 / 200 / 300 V | 2.29 | 4.10 | 5.45 | 6.94 | 13.48 | 25.38* |

*The main deviation factor is high temperature condition. The Total CC tolerance at 1% deep dimming condition without high temperature condition is less than 20%.

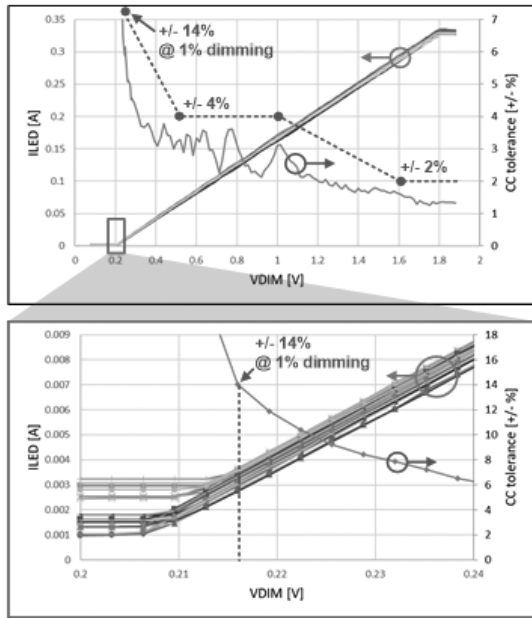


Figure 12. NCL30076 Dimming Curve and CC Tolerance

Standby Mode

Standby mode is triggered by V_{DIM} as shown in Figure 13.

- **A:** When V_{DIM} is lower than V_{DIM(SB-ENA)}, DRV is shut down. So, LED lamps turn off.
- **B:** After t_{SB(Delay)} (10 ms), standby mode is entered and NCL30076 current consumption drops to I_{DD(SB)}.
- **C:** When V_{DIM} is higher than V_{DIM(SB-DIS)}, standby mode is immediately terminated and IC starts up.

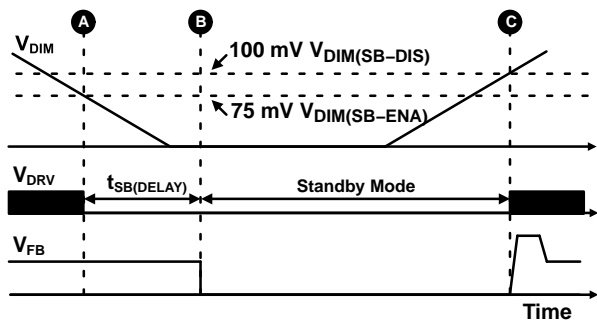


Figure 13. NCL30076 Standby Mode

Soft Start

During soft start operation, Internal soft start counter T_{OFF,SS} contributes to T_{OFF} by reduced from t_{OFF(max)}. When T_{OFF,SS} reaches to the steady state level, V_{FB} is settled to regulation level and T_{OFF} is finally decided to T_{OFF,FB} or T_{OFF,ZCD} by load condition. In the end of the soft start time, T_{OFF,SS} reaches to 0 and doesn't affect T_{OFF} control anymore. Figure 14 shows how the soft start operates at full load condition where T_{OFF,FB} is not engaged as T_{OFF} is set by T_{OFF,ZCD} in QR mode.

- **A:** T_{OFF} is determined by T_{OFF,SS} which is reduced from t_{OFF(MAX)}. V_{FB} is pulled up and the system operates in DCM mode.
- **B:** T_{OFF} is controlled by T_{OFF,ZCD} as T_{OFF,SS} is shorter than T_{OFF,ZCD}. V_{LED} is closer to V_{REF}, and V_{FB} starts falling.
- **C:** V_{FB} is settled in regulation level and steady state starts.

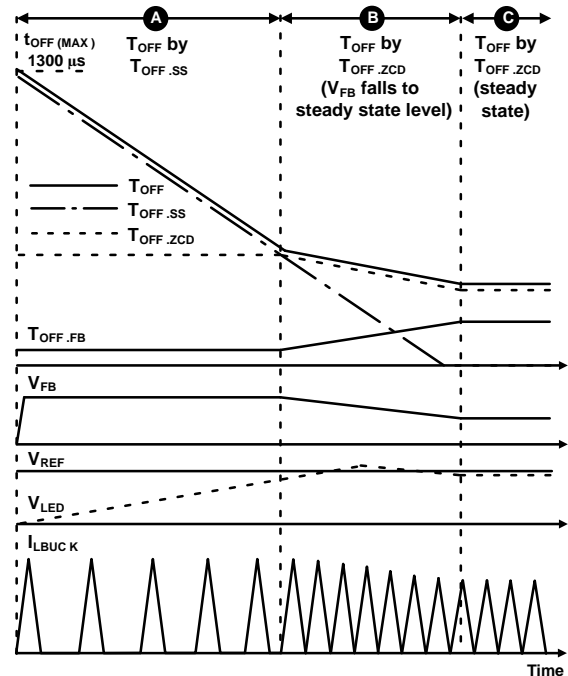


Figure 14. Soft Start Sequence (Full Load Startup in QR)

Protections

- VDD Over Voltage Protection (OVP)

When VDD is higher than $V_{DD(OVP)}$ (23 V), VDD OVP is triggered with 1 sec AR timer. Open LED protection can be implemented by VDD OVP when VDD is supplied by auxiliary winding in the buck inductor.

- Over Current Protection (OCP)

When CSZCD voltage is higher than $V_{CS(OCP)}$ (1 V) after leading edge blanking time, $t_{LEB(TON)}$ (400 ns), IC immediately shuts down with 1 sec AR timer.

- Short LED Protection (SLP)

When LED load is short-circuited, T_{OFF} is lengthened to

1300 μ s, $t_{OFF(MAX)}$ due to the absence of zero cross detection. Therefore, max. T_{OFF} control protects the freewheeling diode from thermal stress and the diode current is regulated close to the LED current set by V_{DIM} .

- Thermal Shut Down (TSD)

When the junction temperature is higher than T_{SD} , the system shuts down and the junction temperature is monitored at every 1 second AR delay time. When the temperature is lower than $T_{SD} - T_{SD(HYS)}$, the system restarts.

APPENDIX: DIMMING CURVE AND CC TOLERANCE WITH SYSTEM VARIABLES

- System: NCL30076 100 W (V_{IN} : 400 V / V_{OUT} : 100 ~ 300 V / $I_{OUT(MAX)}$: 333 mA)
- Temperature variation: -10 / 25 / 90 °C
- Inductance variation: $\pm 15\%$ (1.36 mH ~ 1.84 mH)
- Output Voltage: 100 / 200 / 300 V
- NCL35076 Controller: 150 pcs (3 lot variation)

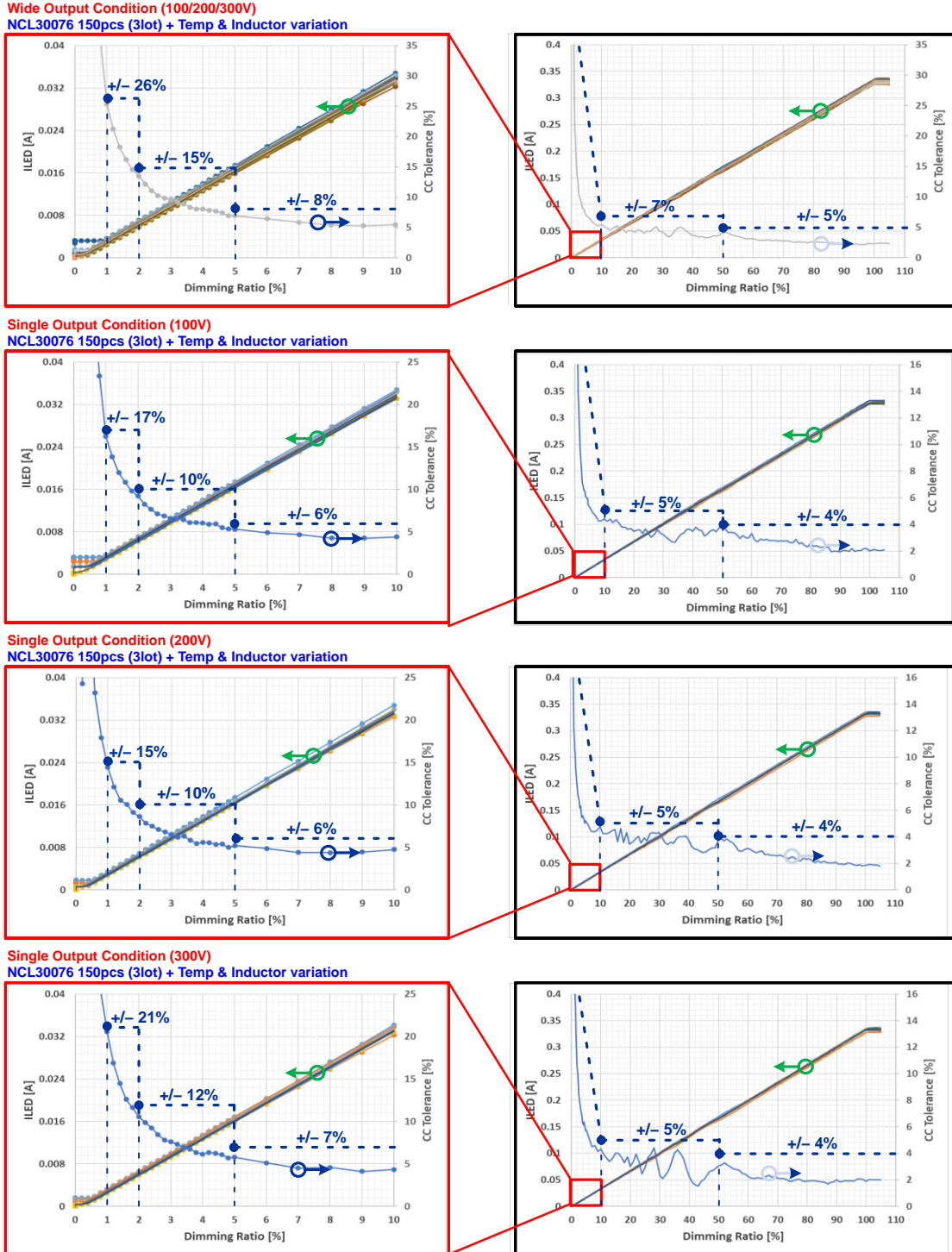
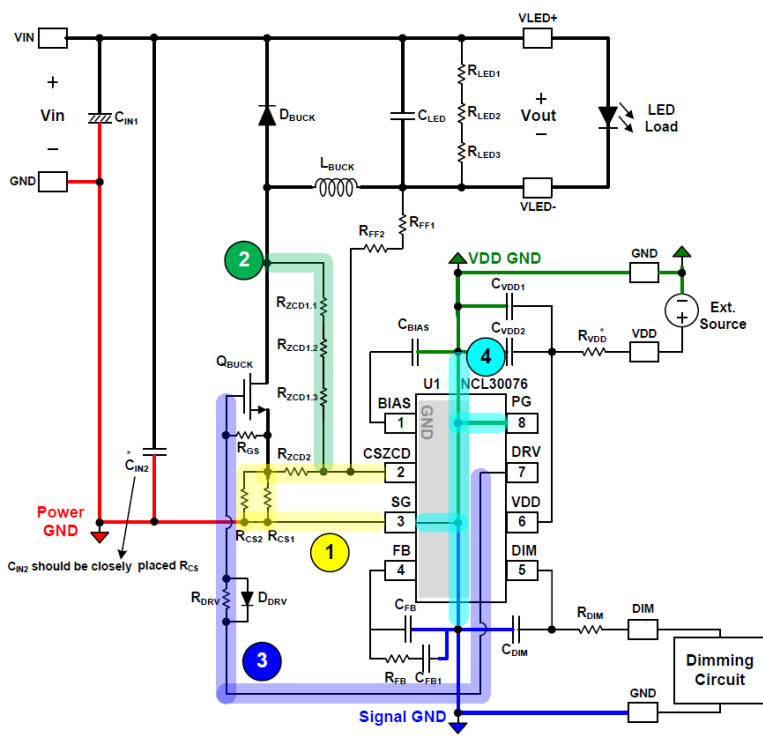


Figure 15. CC Tolerance (150 pcs)

PCB LAYOUT GUIDANCE



Layout guidance 1

Current sensing path (CSZCD - R_{ZCD2} - R_{CS} - SG) should be **short**. This path and IC should be **away** from L_{BUCK}.

Layout guidance 2

1. CSZCD node should be **away** from Drain node.
2. R_{ZCD1} resistors should be **close** each other.

| Series | Zigzag | 90° angle |
|--------|--------|-----------|
| | | |

3. R_{ZCD1} type guidance
- Three 1206 (3216) SMD resistors
- Two axial resistor

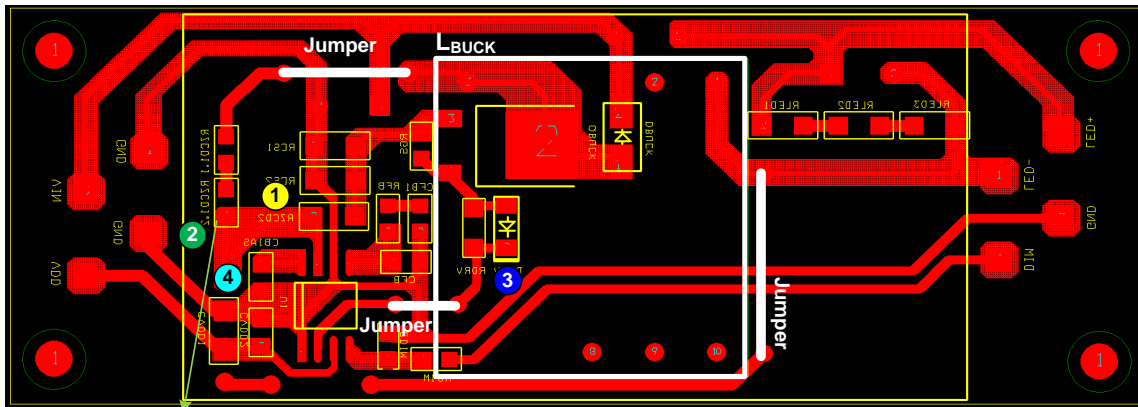
Layout guidance 3

FB and DIM node should be **away** from DRV node

Layout guidance 4

BIAS and VDD circuits are connected to VDD GND (= PG pin).
FB and DIM circuits are connected to Signal GND.
VDD GND and Signal GND join at the bottom of IC with SG connection.

*** Important!!**
RVDD and CIN2 must be added for improving switching noise immunity



* RZCD1 should be properly selected according to rated voltage.

Figure 16. Layout Guidance

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 1:1

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CASE 751-07
ISSUE AK

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- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

| DIM | MILLIMETERS | | INCHES | |
|-----|-------------|------|-----------|-------|
| | MIN | MAX | MIN | MAX |
| A | 4.80 | 5.00 | 0.189 | 0.197 |
| B | 3.80 | 4.00 | 0.150 | 0.157 |
| C | 1.35 | 1.75 | 0.053 | 0.069 |
| D | 0.33 | 0.51 | 0.013 | 0.020 |
| G | 1.27 BSC | | 0.050 BSC | |
| H | 0.10 | 0.25 | 0.004 | 0.010 |
| J | 0.19 | 0.25 | 0.007 | 0.010 |
| K | 0.40 | 1.27 | 0.016 | 0.050 |
| M | 0° | 8° | 0° | 8° |
| N | 0.25 | 0.50 | 0.010 | 0.020 |
| S | 5.80 | 6.20 | 0.228 | 0.244 |

GENERIC MARKING DIAGRAM*

SOLDERING FOOTPRINT*



XXXXXX = Specific Device Code
A = Assembly Location
L = Wafer Lot
Y = Year
W = Work Week
■ = Pb-Free Package

XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
■ = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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- | | | | |
|---|--|--|--|
| <p>STYLE 1: PIN 1. EMITTER 2. COLLECTOR 3. COLLECTOR 4. EMITTER 5. EMITTER 6. BASE 7. BASE 8. EMITTER</p> | <p>STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. BASE, #2 6. EMITTER, #2 7. BASE, #1 8. EMITTER, #1</p> | <p>STYLE 3: PIN 1. DRAIN, DIE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. GATE, #2 6. SOURCE, #2 7. GATE, #1 8. SOURCE, #1</p> | <p>STYLE 4: PIN 1. ANODE 2. ANODE 3. ANODE 4. ANODE 5. ANODE 6. ANODE 7. ANODE 8. COMMON CATHODE</p> |
| <p>STYLE 5: PIN 1. DRAIN 2. DRAIN 3. DRAIN 4. DRAIN 5. GATE 6. GATE 7. SOURCE 8. SOURCE</p> | <p>STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN 4. SOURCE 5. SOURCE 6. GATE 7. GATE 8. SOURCE</p> | <p>STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS 3. THIRD STAGE SOURCE 4. GROUND 5. DRAIN 6. GATE 3 7. SECOND STAGE Vd 8. FIRST STAGE Vd</p> | <p>STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 3. BASE, #2 4. COLLECTOR, #2 5. COLLECTOR, #2 6. EMITTER, #2 7. EMITTER, #1 8. COLLECTOR, #1</p> |
| <p>STYLE 9: PIN 1. EMITTER, COMMON 2. COLLECTOR, DIE #1 3. COLLECTOR, DIE #2 4. EMITTER, COMMON 5. EMITTER, COMMON 6. BASE, DIE #2 7. BASE, DIE #1 8. EMITTER, COMMON</p> | <p>STYLE 10: PIN 1. GROUND 2. BIAS 1 3. OUTPUT 4. GROUND 5. GROUND 6. BIAS 2 7. INPUT 8. GROUND</p> | <p>STYLE 11: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. DRAIN 2 7. DRAIN 1 8. DRAIN 1</p> | <p>STYLE 12: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN</p> |
| <p>STYLE 13: PIN 1. N.C. 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN</p> | <p>STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3. P-SOURCE 4. P-GATE 5. P-DRAIN 6. P-DRAIN 7. N-DRAIN 8. N-DRAIN</p> | <p>STYLE 15: PIN 1. ANODE 1 2. ANODE 1 3. ANODE 1 4. ANODE 1 5. CATHODE, COMMON 6. CATHODE, COMMON 7. CATHODE, COMMON 8. CATHODE, COMMON</p> | <p>STYLE 16: PIN 1. EMITTER, DIE #1 2. BASE, DIE #1 3. EMITTER, DIE #2 4. BASE, DIE #2 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 7. COLLECTOR, DIE #1 8. COLLECTOR, DIE #1</p> |
| <p>STYLE 17: PIN 1. VCC 2. V2OUT 3. V1OUT 4. TXE 5. RXE 6. VEE 7. GND 8. ACC</p> | <p>STYLE 18: PIN 1. ANODE 2. ANODE 3. SOURCE 4. GATE 5. DRAIN 6. DRAIN 7. CATHODE 8. CATHODE</p> | <p>STYLE 19: PIN 1. SOURCE 1 2. GATE 1 3. SOURCE 2 4. GATE 2 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. MIRROR 1</p> | <p>STYLE 20: PIN 1. SOURCE (N) 2. GATE (N) 3. SOURCE (P) 4. GATE (P) 5. DRAIN 6. DRAIN 7. DRAIN 8. DRAIN</p> |
| <p>STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3. CATHODE 3 4. CATHODE 4 5. CATHODE 5 6. COMMON ANODE 7. COMMON ANODE 8. CATHODE 6</p> | <p>STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3. COMMON CATHODE/VCC 4. I/O LINE 3 5. COMMON ANODE/GND 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND</p> | <p>STYLE 23: PIN 1. LINE 1 IN 2. COMMON ANODE/GND 3. COMMON ANODE/GND 4. LINE 2 IN 5. LINE 2 OUT 6. COMMON ANODE/GND 7. COMMON ANODE/GND 8. LINE 1 OUT</p> | <p>STYLE 24: PIN 1. BASE 2. EMITTER 3. COLLECTOR/ANODE 4. COLLECTOR/ANODE 5. CATHODE 6. CATHODE 7. COLLECTOR/ANODE 8. COLLECTOR/ANODE</p> |
| <p>STYLE 25: PIN 1. VIN 2. N/C 3. REXT 4. GND 5. IOUT 6. IOUT 7. IOUT 8. IOUT</p> | <p>STYLE 26: PIN 1. GND 2. dv/dt 3. ENABLE 4. ILIMIT 5. SOURCE 6. SOURCE 7. SOURCE 8. VCC</p> | <p>STYLE 27: PIN 1. ILIMIT 2. OVLO 3. UVLO 4. INPUT+ 5. SOURCE 6. SOURCE 7. SOURCE 8. DRAIN</p> | <p>STYLE 28: PIN 1. SW_TO_GND 2. DASIC_OFF 3. DASIC_SW_DET 4. GND 5. V_MON 6. VBULK 7. VBULK 8. VIN</p> |
| <p>STYLE 29: PIN 1. BASE, DIE #1 2. EMITTER, #1 3. BASE, #2 4. EMITTER, #2 5. COLLECTOR, #2 6. COLLECTOR, #2 7. COLLECTOR, #1 8. COLLECTOR, #1</p> | <p>STYLE 30: PIN 1. DRAIN 1 2. DRAIN 1 3. GATE 2 4. SOURCE 2 5. SOURCE 1/DRAIN 2 6. SOURCE 1/DRAIN 2 7. SOURCE 1/DRAIN 2 8. GATE 1</p> | | |

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